



# IMEC UPDATE ON RESIST OUTGASSING QUALIFICATION

**I. POLLENTIER, R. LOKASANI, AND R. GRONHEID**



# OUTLINE

Imec infrastructure and qualification results

Simple RGA approach to quantify cleanable and non-cleanable contamination

Correlation of simple RGA approach to NXEWS results

EUV vs. E-gun resist exposure mode

Summary

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## Imec infrastructure and qualification results

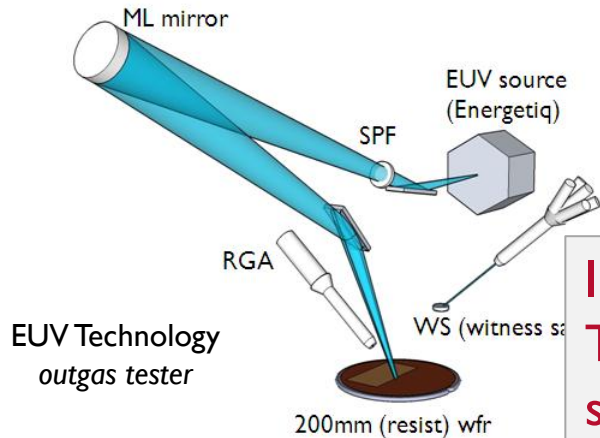
Simple RGA approach to quantify cleanable and non-cleanable contamination

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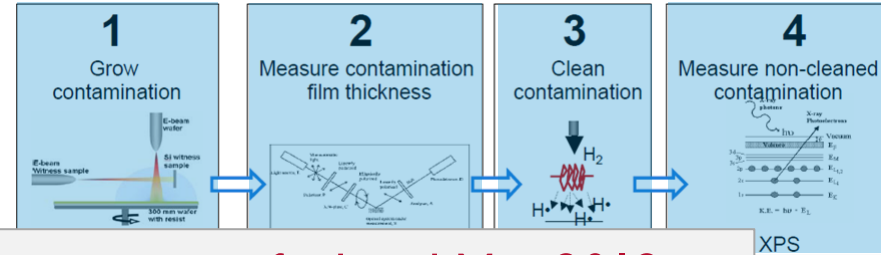
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# RESIST OUTGASSING QUALIFICATION PROCEDURE FOR NXE3x00



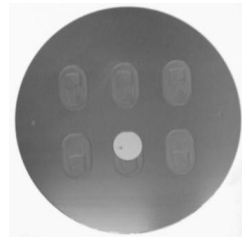
EUV Technology outgas tester



Imec infrastructure was certified end May 2012.  
The issue with H-cleaner sulfur background is solved in August.  
Currently, the infrastructure allows to test ~20 materials per month.



KLA-tencor UV1280 ellipsometer



200mm Pocket-wafer with 6 available positions for 1" WS



EUV Technology H-filament cleaner

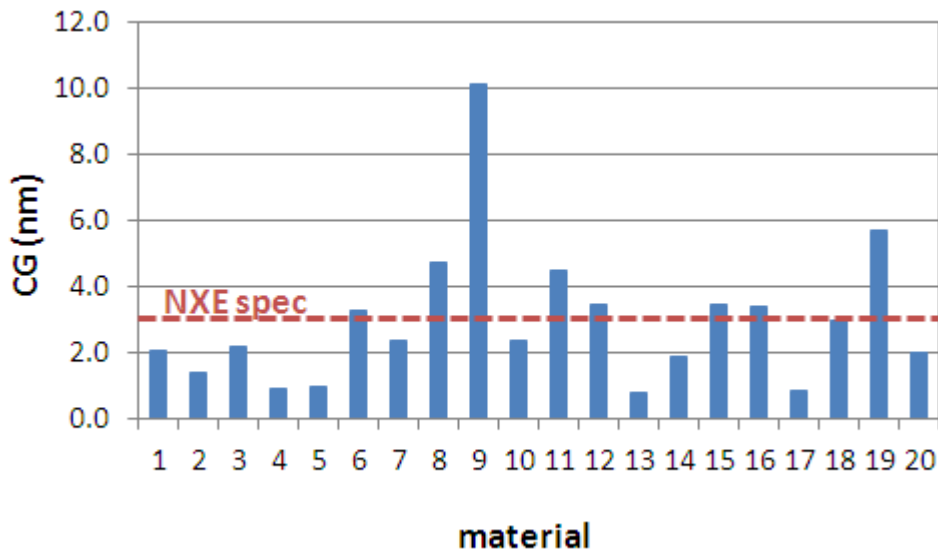


Thermo Instruments Theta 300 XPS

# CURRENT QUALIFICATION RESULTS

## Cleanable contamination

- ▶ Resist related contamination growth (CG) of 20 resists (commercial and model) was determined using NXE qualification method.

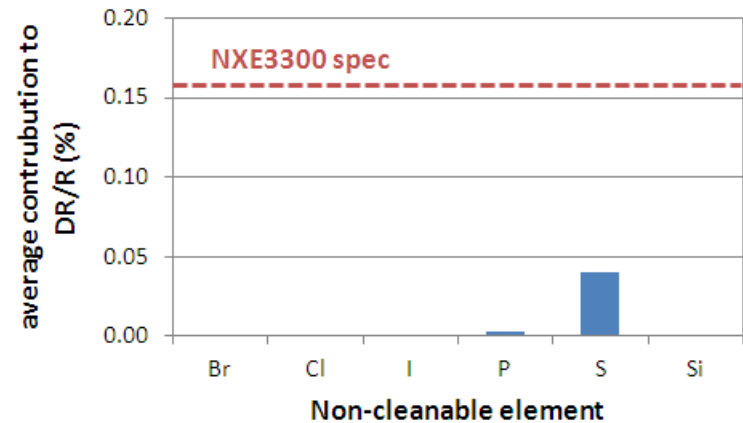
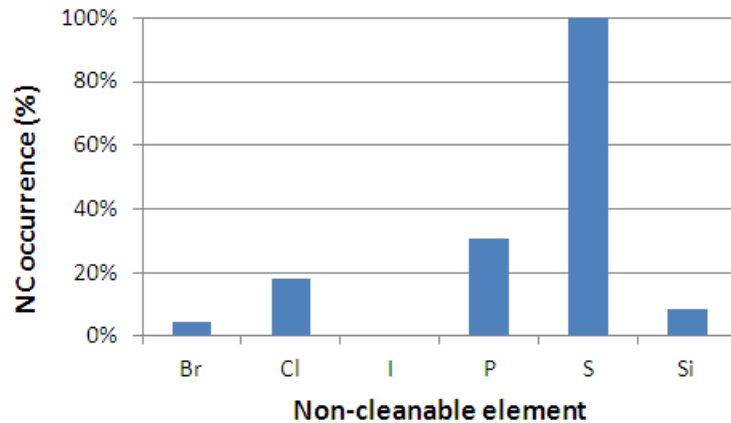


Most commercial materials meet the NXE spec for cleanable contamination (<3nm), but variation of CG thickness can be obtained depending on the chemistry of the (model) resists and its dose.

# CURRENT QUALIFICATION RESULTS

## Non-cleanable contamination

- ▶ Resist related contamination of 23 resists (commercial and model) was analyzed by XPS



Sulphur appears consistently in all measurements and has in average the highest contribution. However the typical contribution seems to be significantly less than the NXE300-spec.

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**Simple RGA approach to quantify cleanable and non-cleanable contamination**

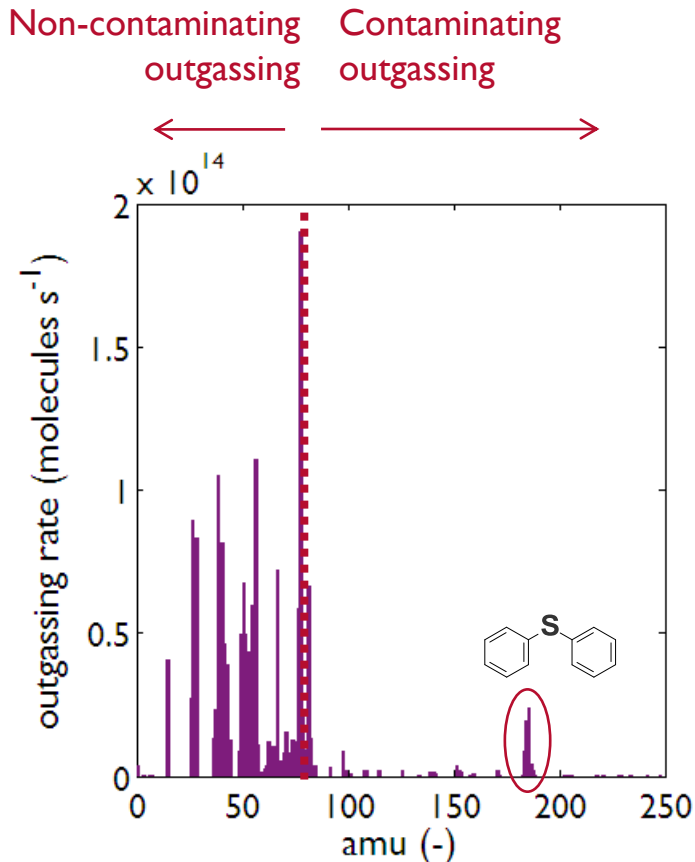
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# RGA APPROACH FOR TESTING CONTAMINATION

WS testing is very relevant for contamination but gives limited information on the mechanism of outgassing and its relation to contamination



RGA can give continuously information on molecular weight (amu) of species that are outgassing.

Earlier work suggests that mostly high amu species contribute to contamination, while low-amu species do not.

[I. Pollentier et al., Proc. of SPIE vol. 7972 (2011) ]

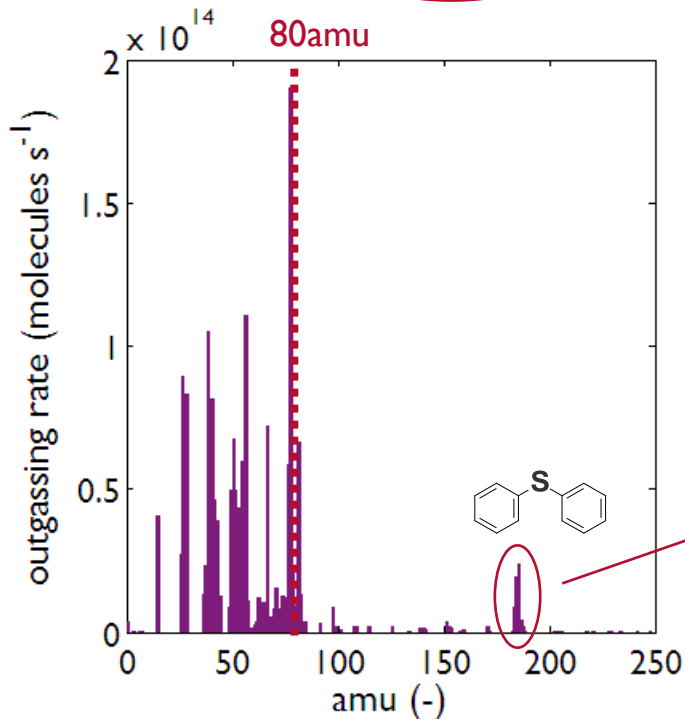
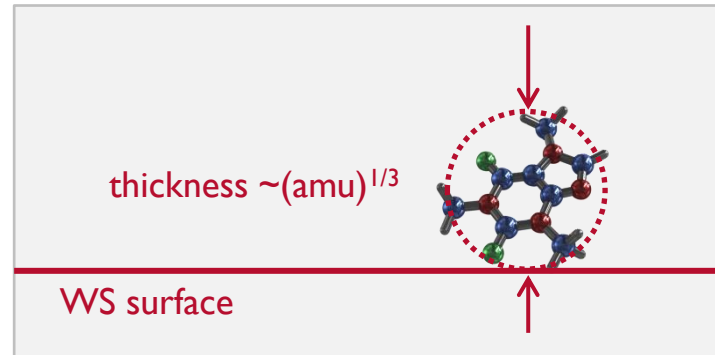
Non-cleanable contamination is typically seen as diphenylsulfide (or comparable) from PAG cation

[I. Pollentier et al., J. Photopolymer Sc. and Techn., Vol 23 (5) (2010)]



# SIMPLE RGA APPROACH TO QUANTIFY THE CONTAMINATION RELATED OUTGASSING

Non-contaminating outgassing      Contaminating outgassing



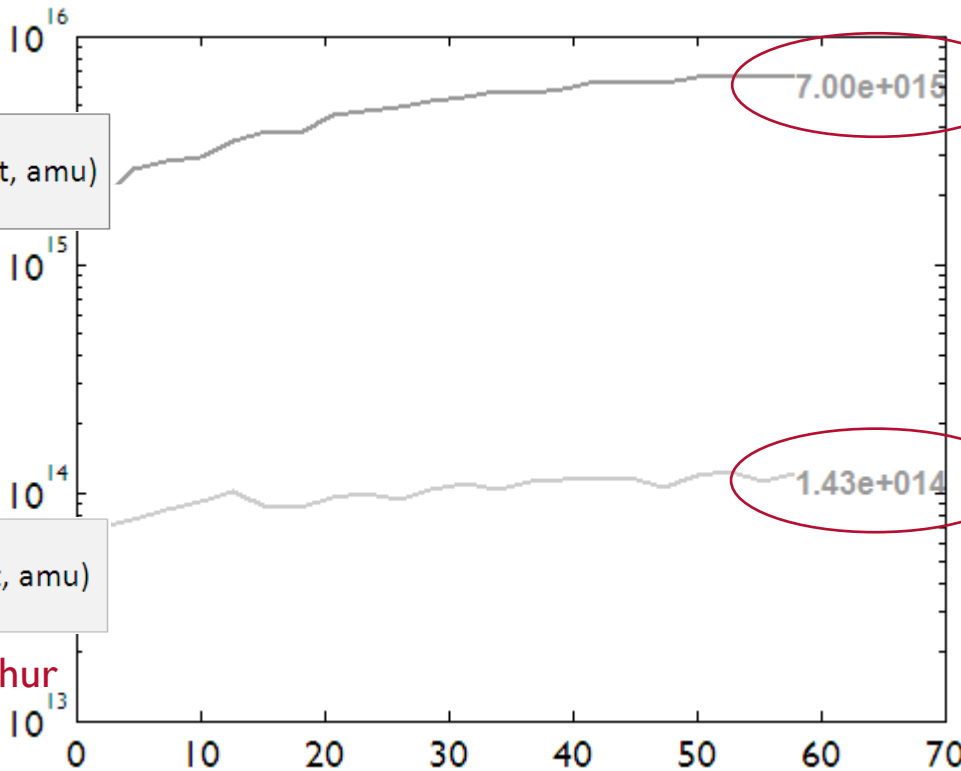
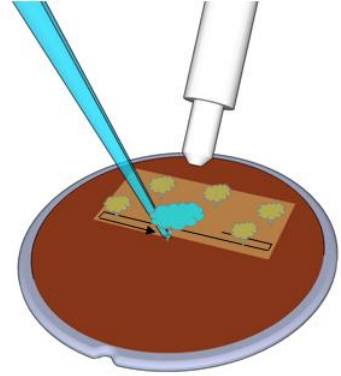
Total cleanable CG rate might be proportional to this outgassing rate :

$$\sum_{\text{amu} = 80}^{250} (\text{amu})^{1/3} \cdot \text{outgas} (t, \text{amu})$$

Non-cleanable sulfur contamination rate might be related to this outgassing rate :

$$\sum_{\text{amu} = 183}^{187} (\text{amu})^{1/3} \cdot \text{outgas} (t, \text{amu})$$

# SIMPLE RGA APPROACH TO QUANTIFY THE CONTAMINATION RELATED OUTGASSING



$$\sum_{amu=80}^{250} (amu)^{1/3} \cdot \text{outgas}(t, amu)$$

'cleanable CG outgassing rate'

$$\int_{t=0}^{1 \text{ hr}} \sum_{amu=80}^{250} (amu)^{1/3} \cdot \text{outgas}(t, amu) \cdot dt$$

'cleanable CG outgassing'

$$\sum_{amu=183}^{187} (amu)^{1/3} \cdot \text{outgas}(t, amu)$$

'non-cleanable sulphur outgassing rate'

$$\int_{t=0}^{1 \text{ hr}} \sum_{amu=183}^{187} (amu)^{1/3} \cdot \text{outgas}(t, amu) \cdot dt$$

'non-cleanable sulphur outgassing'

Integration of this outgassing rate is done over the time of evaluation (1hr); Outgassing rate is increasing due to the 'post-exposure' outgassing.

**Complex RGA information can be condensed in 2 parameters. Do they correlate with NXE qualification results ?**

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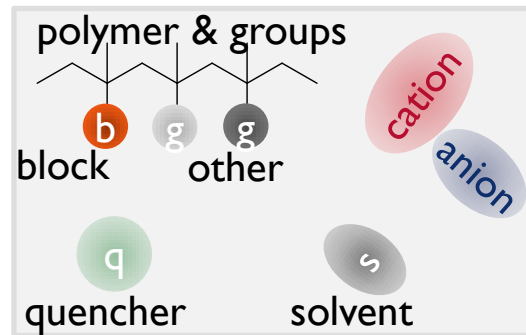
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# CORRELATION OF RGA AND NXE FOR A LARGE RESIST FAMILY

In collaboration with JSR a DOE was done with 12 model resist with major chemical changes :

Different PAG chemistry and mixtures of PAGs  
Different protection groups (low and high activation energy)  
and mixing the groups in different ratios



Changes are much more than  
in earlier family definition.

I. Pollentier et al., Proc. of SPIE vol. 7972 (2011)

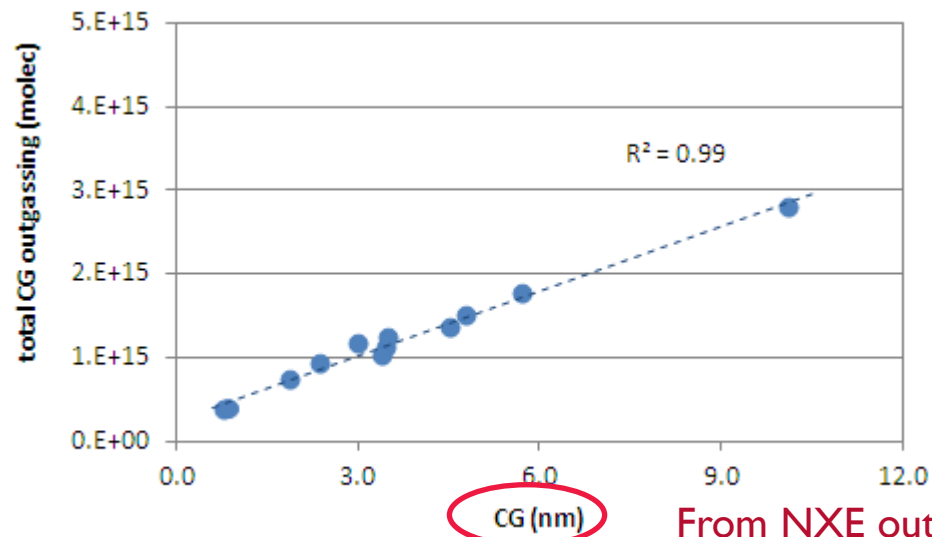
# CORRELATION OF RGA AND NXE FOR A LARGE RESIST FAMILY

Different PAG chemistry and mixtures of PAGs  
Different protection groups (low and high activation energy)  
and mixing the groups in different ratios

Very good correlation is found !!!  
Preliminary further tests show that model even works for adding UL or TC's !!!

'cleanable CG outgassing'

$$\int_{t=0}^{1 \text{ hr}} \sum_{\text{amu} = 80}^{250} (\text{amu})^{1/3} \cdot \text{outgas}(t, \text{amu}) \cdot dt$$



From NXE outgassing  
WS test !

# CORRELATION OF RGA AND NXE FOR A LARGE RESIST FAMILY

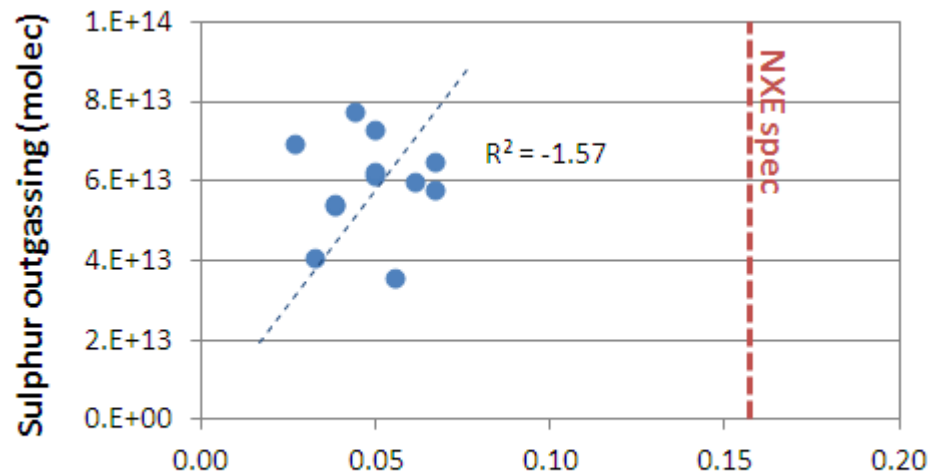
Different PAG chemistry and mixtures of PAGs  
 Different protection groups (low and high activation energy)  
 and mixing the groups in different ratios

Poor correlation (possibly due to the very long H-cleaning time for some samples), but all well below the NXE-spec.

Other test-case gives better correlation, see Symposium presentation

non-cleanable sulphur contamination ~

$$\int_{t=0}^{1 \text{ hr}} \sum_{\text{amu} = 183}^{187} (\text{amu})^{1/3} \cdot \text{outgas}(t, \text{amu}) \cdot dt$$



XPS based Sulphur DR/R (%) From NXE outgassing WS test !

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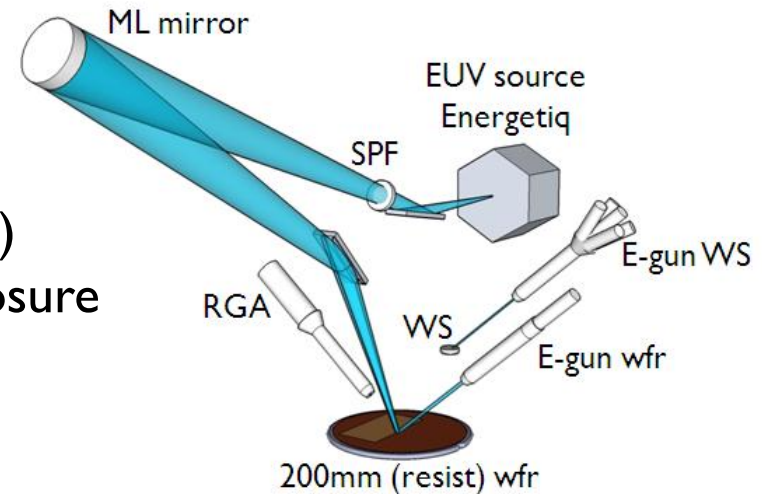
Summary

# EUV vs. EGUN EXPOSURE ON WAFER

Imec set-up is equipped with Egun for resist exposure, therefore CG can be compared between EUV vs. Egun exposure

Differences are observed :

- ▶ Over-all Egun gives less (cleanable) contamination than EUV wfr exposure
- ▶ Resist dependency



It is planned to investigate further the differences between EUV and E-gun exposure, using again the RGA as intermediate step to detect any differences in dynamic outgassing and composition.



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In the early experience of NXE resist outgas qualification cleanable contamination (chemistry, dose) seems more critical than non-cleanable contamination (mainly sulphur).

A simple RGA method is proposed based on weighted contribution of outgassing for cleanable and non-cleanable contamination.

This model lines up very well for cleanable contamination ( $R^2$  up to 99% !) for a wide range of materials, which should contribute to faster learning and testing.

# ACKNOWLEDGEMENTS

T. Conard (imec) for XPS support and helpful discussions

R. Perera and D. Houser (EUV Technology) for tool support

K. Hoshiko and G. Goossens (JSR) for help in testing materials and helpful discussions